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The marking on this product doesn't contain environmental hazardous materials per Material Specification 55-00259 for Sony GP compliant or per directive 2011/65/EU for RoHS compliant.



ORIGINAL

PART NO. G881AXX0X1TXEU

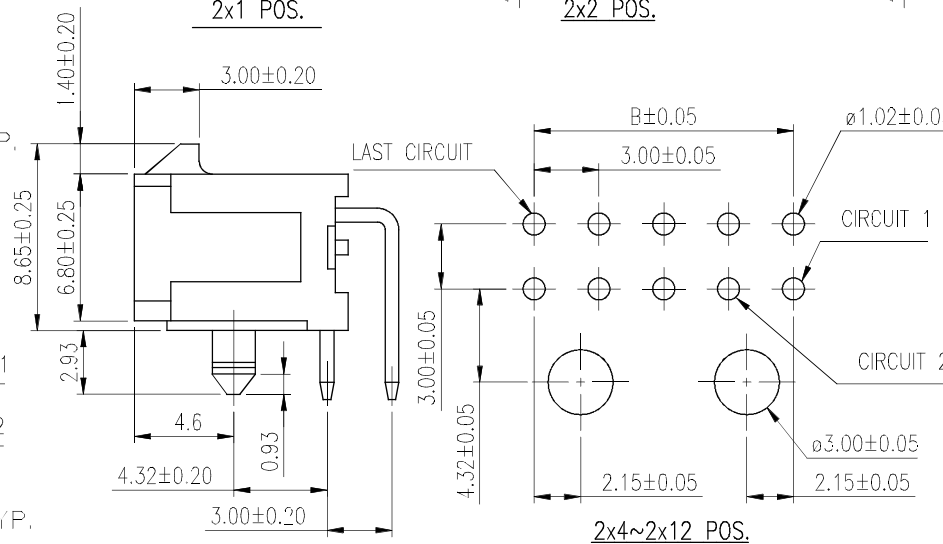
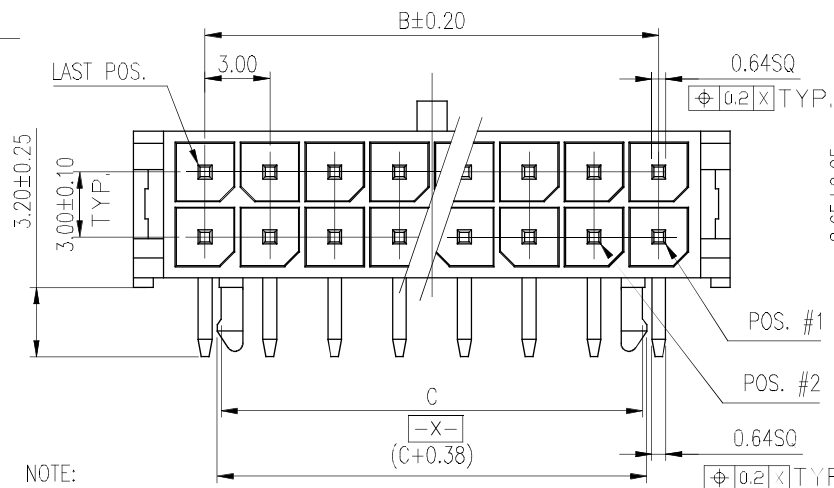
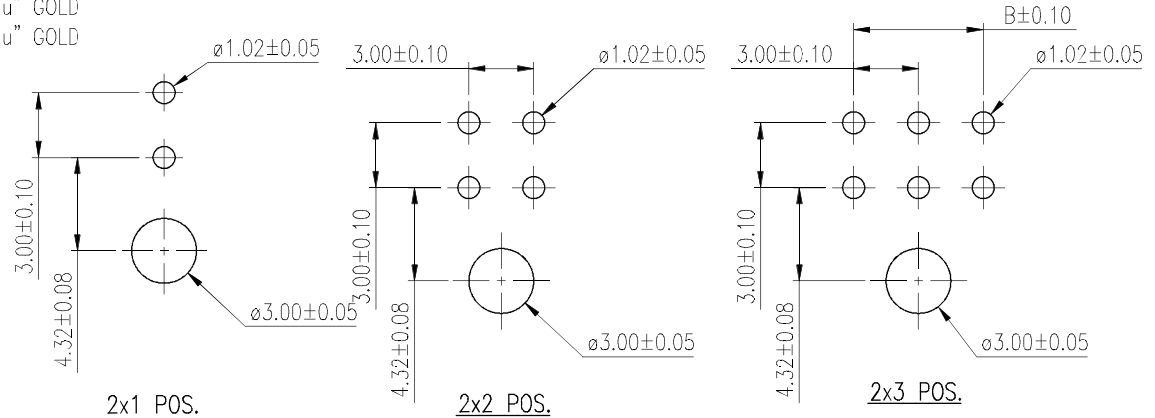
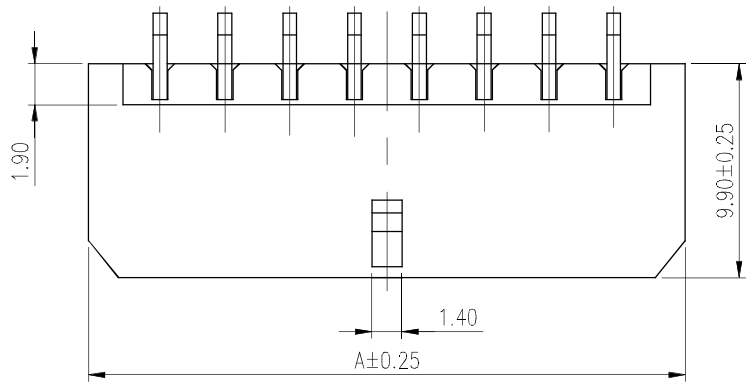
No. OF CIRCUIT

PACKING OPTIONS
BLANK : TRAY
R : T&R



REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A		RELEASE FOR RoHS	10/06/2005	Henry Ko
B	NE-11044	DRAWING UPDATE	03/28/2011	Arron Lin
C	NE-12011	ADDED DIM. 4.6 & 0.93	02/10/2012	Arron Lin
D	NE-13023	ADDED 30u" GOLD	01/31/2013	Arron Lin
E	NE-17133	UPDATE DRAWING/ADDED T&R PACKAGE	06/19/2017	Roger Tsai

CONTACT FINISH
0: 100u" MATTE TIN PLATING (OVERALL)
1: GOLD FLASH (OVERALL)
2: 15u" GOLD
3: 30u" GOLD



24	39.60	33.00	31.50
22	36.60	30.00	28.50
20	33.60	27.00	25.50
18	30.60	24.00	22.50
16	27.60	21.00	19.50
14	24.60	18.00	16.50
12	21.60	15.00	13.50
10	18.60	12.00	10.50
08	15.60	9.00	7.50
06	12.60	6.00	2.80
04	9.60	3.00	2.80
02	6.60	NA	2.80
NO. OF CIRCUIT	A	B	C

NOTE:

- INSULATOR: HIGH TEMP. THERMOPLASTIC, LCP, UL 94V-0, COLOR BLACK
- CONTACT MATERIAL: COPPER ALLOY.
- FINISH:
CONTACT AREA: SELECTIVE PLATING;
SOLDERING AREA: MATTE TIN PLATING OR GOLD PLATING;
UNDER PLATING: NICKEL PLATING 50 μ" THICKNESS MIN. OVERALL.
- THIS PRODUCT DOESN'T ENVIRONMENTAL HAZARDOUS MATERIALS PER DIRECTIVE 2011/65/EU FOR RoHS.
- APPLICABLE P.C.BOARD THICKNESS: 1.60mm
- PACKING MUST BE PER Amphenol PACKING SPECIFICATION

RECOMMENDED PCB LAYOUT

TOLERANCE	APPROVALS	DATE	TITLE		UNIT		SIZE	PART No.
X. ±0.30	DRAWN Karen Su	06/19/2017	G881A SERIES WIRE TO BOARD, WAFER 3.00 MM PITCH R/A PCB MOUNT		mm	A3	G881AXX0X1TXEU	
X.X ±0.20	CHECKED Aqua Chou	06/19/2017						
X.XX ±0.10	APPROVED Roger Tsai	06/19/2017						
ANGULAR ±1°	DWG TYPE CUST DWG	PROJECT CODE PHD	SCALE NA		SHEET 1 OF 4	DWG No. G881AXX0X1TXEU	REV. E	

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The marking on this product doesn't contain environmental hazardous materials per Material Specification 55-00759 for Sony GP compliant or per directive 2011/65/EU for RoHS compliant.

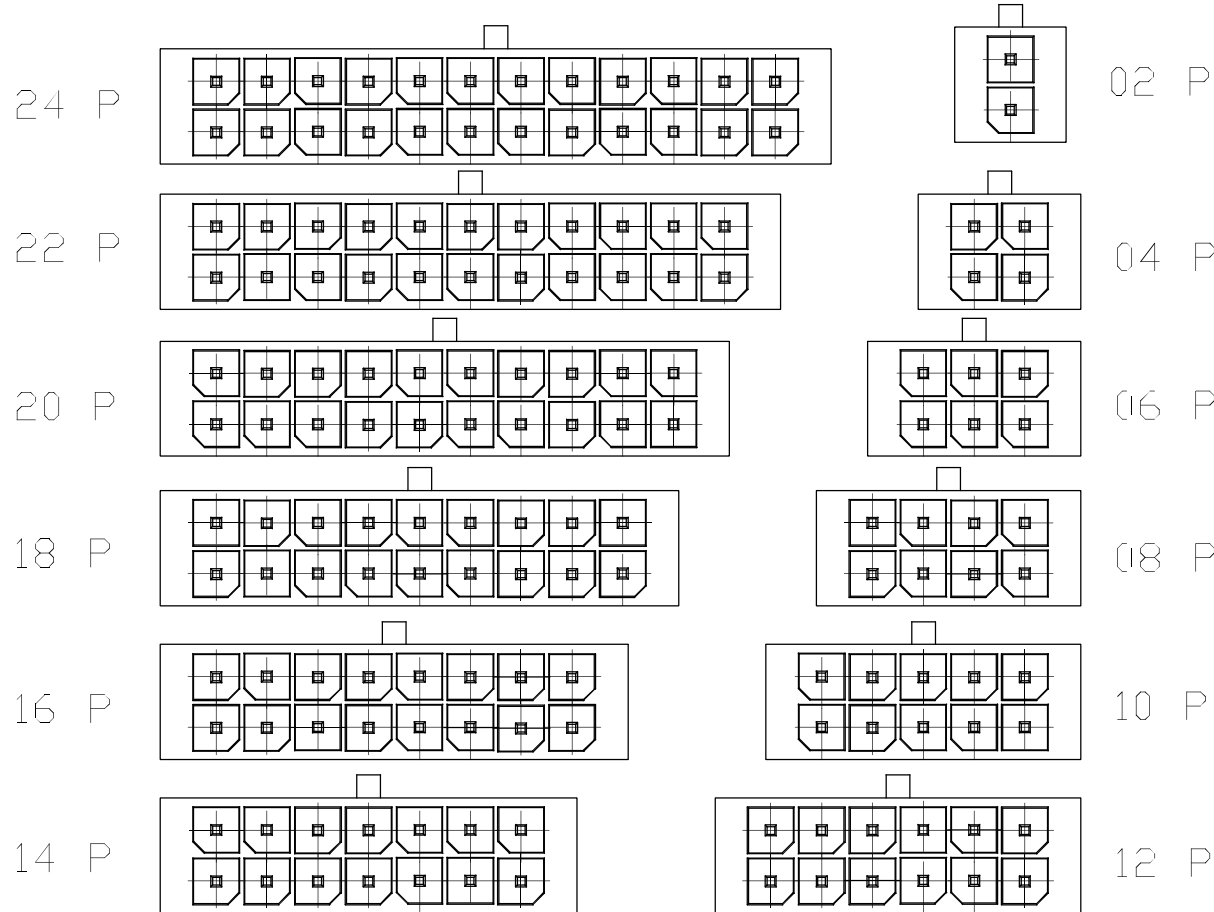


ORIGINAL

02~24 PIN TOP VIEW



REVISIONS				
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C	NE-12011	ADDED DIM. 4.6 & 0.93	02/10/2012	Arron Lin
D	NE-13023	ADDED 30u" GOLD	01/31/2013	Arron Lin
E	NE-17133	UPDATE DRAWING/ADDED T&R PACKAGE	06/19/2017	Roger Tsai



TOLERANCE		APPROVALS		DATE	TITLE			Amphenol [®] Amphenol Corporation Amphenol Taiwan Corporation		
X.		DRAWN	Karen Su	06/19/2017	G881A SERIES WIRE TO BOARD, WAFER 3.00 MM PITCH R/A PCB MOUNT			PART No. G881AXX0X1TXEU		
X.X	±0.30	CHECKED	Aqua Chou	06/19/2017				SHEET 2 OF 4		
X.XX	±0.20	APPROVED	Roger Tsai	06/19/2017						
X.XXX	±0.10	UNLESS OTHERWISE SPECIFIED		DWG TYPE	PROJECT CODE	SCALE			DWG No. G881AXX0X1TXEU	
ANGULAR	±1°	CUST DWG		PHD	UNIT mm	SIZE A3	REV. E			

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426(L)*262.5(W)*10(H)

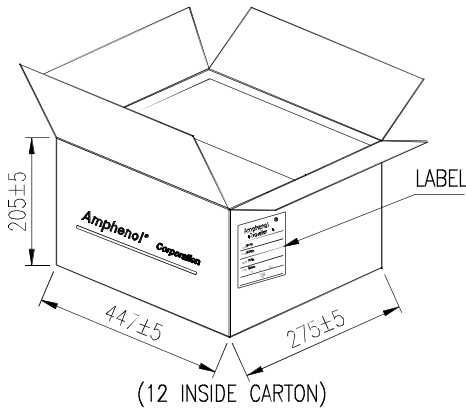
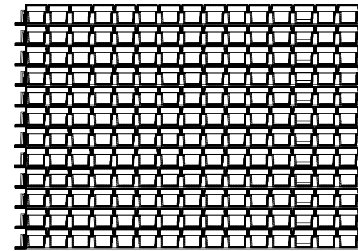
426(L)*262.5(W)*14(H)



TRAY BOTTOM COVER



TRAY TOP COVER



POS	PCS/TRAY	PCS/CARTON
02	900	10800
04	615	7380
06	465	5580
08	375	4500
10	315	3780
12	270	3240
14	240	2880
16	210	2520
18	180	2160
20	165	1980
22	150	1800
24	150	1800

NOTE:

1. MATERIAL : BLACK CONDUCTIVE POLYSTYRENE ALLOY
2. ALL DIMENSIONS MEET EIA-481-C REQUIREMENTS.
3. THICKNESS : 0.80±0.05mm.

TOLERANCE	APPROVALS	DATE	TITLE			PART No.		
X. ±0.30	DRAWN Karen Su	06/19/2017	G881A SERIES WIRE TO BOARD, WAFER 3.00 MM PITCH R/A PCB MOUNT			Amphenol® Amphenol Corporation Amphenol Taiwan Corporation		
X.X ±0.20	CHECKED Aqua Chou	06/19/2017						
X.XXX ±0.10	APPROVED Roger Tsai	06/19/2017						
ANGULAR ±1°	DWG TYPE CUST DWG	PROJECT CODE PHD	UNIT mm	SIZE A3	G881AXX0X1TXEU			
UNLESS OTHERWISE SPECIFIED			SCALE NA	SHEET 3 OF 4	DWG No. G881AXX0X1TXEU		REV. E	

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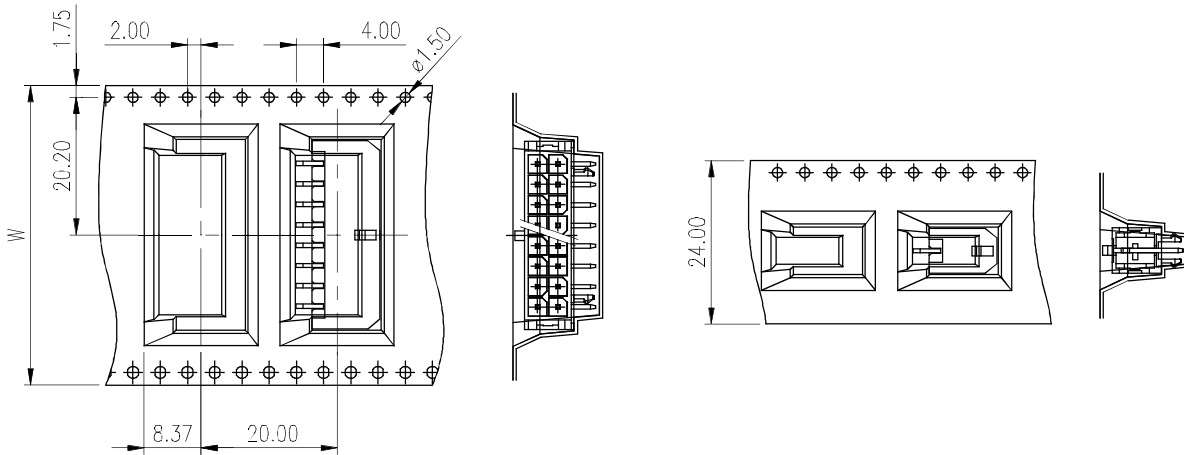
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ORIGINAL

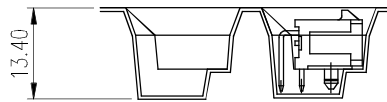
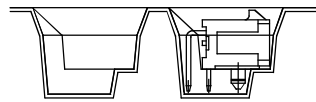


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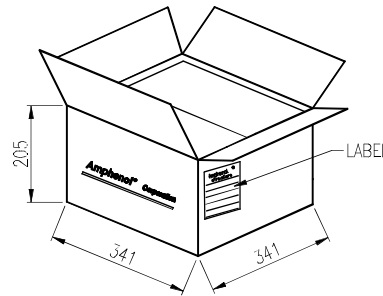
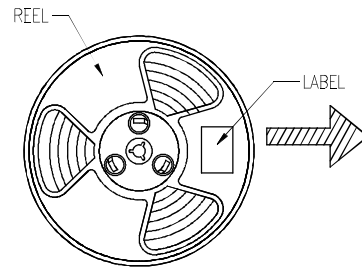
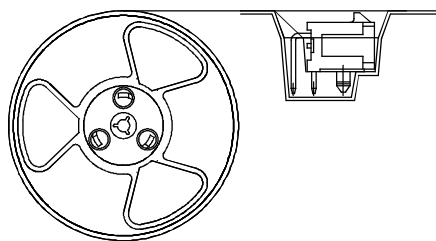


NOTE:

1. MATERIAL : BLACK CONDUCTIVE POLYSTYRENE ALLOY
2. ALL DIMENSIONS MEET EIA-481-C REQUIREMENTS.
3. THICKNESS : 0.50±0.05mm.
4. THIS PRODUCT DOESN'T CONTAIN ENVIRONMENTAL HAZARDOUS MATERIALS PER DIRECTIVE 2011/65/EU FOR RoHS



PULL OUT DIRECTION



P-CKAGING BY TAPE&REEL	PART NO.	POS.	DIM"W"	PCS REEL	QUANTITY (PCS)
	G881A020X1TREU	02	24	200	1200
	G881A040X1TREU	04	24	200	1200
	G881A060X1TREU	06	32	200	1000
	G881A080X1TREU	08	32	200	1000
	G881A100X1TREU	10	44	200	800
	G881A120X1TREU	12	44	200	800
	G881A140X1TREU	14	44	200	800
	G881A160X1TREU	16	44	200	800
	G881A180X1TREU	18	44	200	800
	G881A200X1TREU	20	56	200	600
G881A220X1TREU	22	56	200	600	
G881A240X1TREU	24	56	200	600	



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X.XXX ±0.10	APPROVED Roger Tsai	06/19/2017			G881AXX0X1TXEU	
ANGULAR ±1°	DWG TYPE CUST DWG	PROJECT CODE PHD	UNIT mm	SIZE A3	REV. E	
UNLESS OTHERWISE SPECIFIED			SCALE NA	SHEET 4 OF 4		